

AMENDMENTS TO THE CLAIMS

Claim 1 (Canceled)

Claim 2 (Currently Amended): A thermosetting resin composition wherein an epoxy resin (Component (c)) which has a number average molecular weight of 7,000 to 35,000, an average functional group number of 2 or more per one molecule, and a functional group equivalent of 2,000 to 18,000 g/mol, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, is incorporated in combination with the Component (A) as set forth in Claim 1 which has a number average molecular weight of 800 to 35,000, an average functional group number of more than 2 per one molecule, and a functional group equivalent of 150 to 2,000 g/mol, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, both resins being incorporated in such ratio that the total average equivalent becomes 300 to 2,000 g/mol (both resins being collectively referred to herein as Component (C)), and a resin (Component (d)) which has a number average molecular weight of 7,000 to 35,000, an average functional group number of 2 or more per one molecule, and a functional group equivalent of 2,000 to 18,000 g/mol, which has one or more functional groups selected from carboxyl group, amino group, acid anhydride group, hydrazide group, mercapto group, hydroxyl group and isocyanate group, and no blocked carboxyl group, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, is incorporated in combination with the Component (B) as set forth in Claim 1 which has a number average molecular weight of 800 to 35,000, an average functional group number of more than 2 per one molecule, and a functional group equivalent of 150 to 2,000 g/mol, which has one or more functional groups selected from amino group, carboxyl group, acid anhydride group, mercapto group, hydroxyl group, isocyanate group and hydrazide group, and no blocked carboxyl group, and which

may have a polybutadiene or hydrogenated polybutadiene skeleton, both resins being incorporated in such ratio that the total average equivalent becomes 300 to 2,000 g/mol (both resins being collectively referred to herein as Component (D)), and wherein the ratio of the Component (D) to the Component (C) is from 0.5 to 2.0 in terms of the overall equivalent number of the functional group (s) of Component (D) capable of reacting with the epoxy group of the Component(C) to the overall equivalent number of the epoxy group of the Component (C).

Claims 3-5 (Canceled)

Claim 6 (Currently Amended): A thermosetting resin composition wherein the Component (A) ~~as set forth in Claim 1 which has a number average molecular weight of 800 to 35, 000, an average functional group number of more than 2 per one molecule, and a functional group equivalent of 150 to 2,000 g/mol, and which may have a polybutadiene or hydrogenated polybutadiene skeleton~~, and a resin (Component (d)) which has a number average molecular weight of 7,000 to 35,000, an average functional group number of 2 or more per one molecule, and a functional group equivalent of 2,000 to 18,000 g/mol, which has one or more functional groups selected from carboxyl group, amino group, acid anhydride group, hydrazide group, mercapto group, hydroxyl group and isocyanate group, and no blocked carboxyl group, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, is incorporated in combination with the Component (B) ~~as set forth in Claim 1 which has a number average molecular weight of 800 to 35,000, an average functional group number of more than 2 per one molecule, and a functional group equivalent of 150 to 2,000 g/mol, which has one or more functional groups selected from amino group, carboxyl group, acid~~

anhydride group, mercapto group, hydroxyl group, isocyanate group and hydrazide group,  
and no blocked carboxyl group, and which may have a polybutadiene or hydrogenated  
polybutadiene skeleton, both resins being incorporated in such ratio that the total average  
equivalent becomes 300 to 2,000 g/mol (both resins being collectively referred to herein as  
Component (D)), and wherein the ratio of the Component (D) to the Component (A) is from  
0.5 to 2.0 in terms of the overall equivalent number of the functional group(s) of Component  
(D) capable of reacting with the epoxy group of the Component (A) to the equivalent number  
of the epoxy group of the Component (A).

Claim 7 (Previously Presented): A thermosetting resin composition wherein an epoxy  
resin (Component (c)) which has a number average molecular weight of 7,000 to 35,000, an  
average functional group number of 2 or more per one molecule, and a functional group  
equivalent of 2,000 to 18,000 g/mol, and which may have a polybutadiene or hydrogenated  
polybutadiene skeleton, is incorporated in combination with the Component (A) as set forth in  
Claim 1which has a number average molecular weight of 800 to 35,000, an average  
functional group number of more than 2 per one molecule, and a functional group equivalent  
of 150 to 2,000 g/mol, and which may have a polybutadiene or hydrogenated polybutadiene  
skeleton, both resins being incorporated in such ratio that the total average equivalent becomes  
300 to 2,000 g/mol (both resins being collectively referred to herein as Component (C)) and the  
Component (B) as set forth in Claim 1 which has a number average molecular weight of 800  
to 35,000, an average functional group number of more than 2 per one molecule, and a  
functional group equivalent of 150 to 2,000 g/mol, which has one or more functional groups  
selected from amino group, carboxyl group, acid anhydride group, mercapto group, hydroxyl  
group, isocyanate group and hydrazide group, and no blocked carboxyl group, and which

may have a polybutadiene or hydrogenated polybutadiene skeleton, and wherein the ratio of the Component (B) to the Component (C) is from 0.5 to 2.0 in terms of the equivalent number of the functional group(s) of Component (B) capable of reacting with the epoxy group of the Component (C) to the overall equivalent number of the epoxy group of the Component (C).

Claim 8 (Currently Amended): An overcoating agent for flexible circuit boards, wherein said thermosetting resin composition as in ~~any one of Claims 1, 2, 6 or 7~~ Claim 2 is employed.

Claim 9 (Previously Presented): A film carrier comprising an insulating film and a pattern formed thereon of metal thin film, with a part or all of the insulating film in the folded region having been removed, wherein the circuit pattern side except the joint region including the folded region, is coated with said overcoating agent of Claim 8 and cured.

Claim 10 (Previously Presented): A film carrier device employing said film carrier of Claim 9.

Claim 11 (New): An overcoating agent for flexible circuit boards, wherein said thermosetting resin composition as in Claim 6 is employed.

Claim 12 (New): A film carrier comprising an insulating film and a pattern formed thereon of metal thin film, with a part or all of the insulating film in the folded region having been removed, wherein the circuit pattern side except the joint region including the folded region, is coated with said overcoating agent of Claim 11 and cured.

Claim 13 (New): A film carrier device employing said film carrier of Claim 12.

Claim 14 (New): An overcoating agent for flexible circuit boards, wherein said thermosetting resin composition as in Claim 7 is employed.

Claim 15 (New): A film carrier comprising an insulating film and a pattern formed thereon of metal thin film, with a part or all of the insulating film in the folded region having been removed, wherein the circuit pattern side except the joint region including the folded region, is coated with said overcoating agent of Claim 14 and cured.

Claim 16 (New): A film carrier device employing said film carrier of Claim 15.

SUPPORT FOR THE AMENDMENTS

Claims 3-5 were previously canceled.

Claims 2 and 6-8 have been amended.

Claims 11-16 have been added.

Support for the amendment of Claims 2, 6, and 7 can be found in previously pending Claims 1, 2, 6, and 7. Further support for the amendment of Claim 6 can be found in Examples 3 and 6, which are presented in Table 1, pages 37-38. Further support for the amendment of Claim 7 can be found in Examples 2, 5, 8, and 11, which are presented in Table 1, pages 37-38. The amendment of Claim 8 and the introduction of new Claims 11-16 are supported by previously pending Claims 8-10 and in original Claims 3-5.

No new matter has been introduced by the present amendment.